

Title (en)  
MODULAR ELECTRONIC BUILDING SYSTEMS WITH MAGNETIC INTERCONNECTIONS AND METHODS OF USING THE SAME

Title (de)  
MODULARE ELEKTRONISCHE GEBÄUDESISTEME MIT MAGNETISCHEN VERBINDUNGEN UND VERFAHREN ZUR VERWENDUNG DAVON

Title (fr)  
SYSTÈMES DE CONSTRUCTION ÉLECTRONIQUE MODULAIRE AVEC INTERCONNEXIONS MAGNÉTIQUES ET LEURS PROCÉDÉS D'UTILISATION

Publication  
**EP 3470127 B1 20201014 (EN)**

Application  
**EP 18184425 A 20130826**

Priority

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- US 2013056599 W 20130826

Abstract (en)  
[origin: WO2014032043A1] Electrical connectors, electrical modules, and systems are provided. In one aspect, an electrical connector includes a housing defining a side surface, an electrical conductor supported by the housing and including an engagement portion proximate the side surface of the housing. The engagement portion is adapted to engage another electrical conductor of another electrical connector. The connector also includes a magnet supported by the housing proximate the side surface of the housing, a projection extending from the side surface of the housing, and a receptacle defined in the side surface of the housing. In other aspects, an electrical module includes at least one of these electrical connectors. In further aspects, a system includes a plurality of these modules and the modules are selectively couplable together.

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